SPECIFICATIONS

PCIe-5763

16-Bit, 500 MS/s, 4-Channel PCI FlexRIO Digitizer Device

This document lists the specifications for the PCIe-5763. Specifications are subject to change without notice. For the most recent device specifications, refer to *ni.com/support*.



Note These specifications are typical at 25 °C unless otherwise noted.

Contents

Definitions	1
Digital I/O	2
Digital I/O Single-Ended Channels	2
Digital I/O High-Speed Serial MGT	3
Reconfigurable FPGA	
Onboard DRAM	
Analog Input	5
General Characteristics	5
Typical Specifications	5
REF/CLK IN	12
General Characteristics	12
Bus Interface	15
Maximum Power Requirements	15
Physical	
Environmental	16
Operating Environment	16
Storage Environment	

Definitions

Warranted specifications describe the performance of a model under stated operating conditions and are covered by the model warranty.

Characteristics describe values that are relevant to the use of the model under stated operating conditions but are not covered by the model warranty.

- *Typical* specifications describe the performance met by a majority of models.
- Nominal specifications describe an attribute that is based on design, conformance testing, or supplemental testing.
- Measured specifications describe the measured performance of a representative model.



Digital I/O

Connector	Molex [™] Nano-Pitch I/O [™]
5.0 V Power	±5%, 50 mA maximum, nominal

Table 1. Digital I/O Signal Characteristics

Signal	Туре	Direction
MGT Tx± <30>1	Xilinx UltraScale GTH	Output
MGT Rx± <30>1	Xilinx UltraScale GTH	Input
DIO <70>	Single-ended	Bidirectional
5.0 V	DC	Output
GND	Ground	_

Digital I/O Single-Ended Channels

Number of channels	8
Signal type	Single-ended
Voltage families	3.3 V, 2.5 V, 1.8 V, 1.5 V, 1.2 V
Input impedance	100 kΩ, nominal
Output impedance	50 Ω, nominal
Direction control	Per channel
Minimum required direction change latency	200 ns
Maximum output toggle rate	$60~\text{MHz}$ with $100~\mu\text{A}$ load, nominal

Table 2. Digital I/O Single-Ended DC Signal Characteristics²

Voltage Family	V _{IL}	V _{IH}	V _{OL} (100μA load)	V _{OH} (100μA load)	Maximum DC Drive Strength
3.3 V	0.8 V	2.0 V	0.2 V	3.0 V	24 mA
2.5 V	0.7 V	1.6 V	0.2 V	2.2 V	18 mA

 $^{^{1}}$ Multi-gigabit transceiver (MGT) signals are available on devices with KU040 and KU060 FPGAs only.

Voltage levels are guaranteed by design through the digital buffer specifications.

Table 2. Digital I/O Single-Ended DC Signal Characteristics² (Continued)

Voltage Family	V _{IL}	V _{IH}	V _{OL} (100μA load)	V _{OH} (100μA load)	Maximum DC Drive Strength
1.8 V	0.62 V	1.29 V	0.2 V	1.5 V	16 mA
1.5 V	0.51 V	1.07 V	0.2 V	1.2 V	12 mA
1.2 V	0.42 V	0.87 V	0.2 V	0.9 V	6 mA

Digital I/O High-Speed Serial MGT³



Note MGTs are available on devices with KU040 and KU060 FPGAs only.

Data rate	500 Mbps to 16.375 Gbps, nominal		
Number of Tx channels	4		
Number of Rx channels	4		
I/O AC coupling capacitor	100 nF		
MGT TX± Channels			
Minimum differential output voltage ⁴	170 mV pk-pk into 100 Ω , nominal		
I/O coupling	AC-coupled with 100 nF capacitor		
MGT RX± Channels			
Differential input voltage range			
≤ 6.6 Gb/s	150 mV pk-pk to 2000 mV pk-pk, nominal		
> 6.6 Gb/s	150 mV pk-pk to 1250 mV pk-pk, nominal		
Differential input resistance	100 Ω , nominal		
I/O coupling	DC-coupled, requires external capacitor A		

Reconfigurable FPGA

PCIe-5763 modules are available with multiple FPGA options. The following table lists the FPGA specifications for the PCIe-5763 FPGA options.

² Voltage levels are guaranteed by design through the digital buffer specifications.

³ For detailed FPGA and High-Speed Serial Link specifications, refer to Xilinx documentation.

⁴ 800 mV pk-pk when transmitter output swing is set to the maximum setting.

Table 3. Reconfigurable FPGA Options

		•	
	KU035	KU040	KU060
LUTs	203,128	242,200	331,680
DSP48 slices (25 × 18 multiplier)	1,700	1,920	2,760
Embedded Block RAM	19.0 Mb	21.1 Mb	38.0 Mb
Default timebase	80 MHz		
Timebase reference sources	Onboard 100 MHz oscillator		
Data transfers	DMA, interrupts, programmed I/O	DMA, interrupts, programmed I/O multi-gigabit transceivers	
Number of DMA channels	60		



Note The Reconfigurable FPGA Options table depicts the total number of FPGA resources available on the part. The number of resources available to the user is slightly lower, as some FPGA resources are consumed by board-interfacing IP for PCI Express, device configuration, and various board I/O. For more information, contact NI support.



Note For FPGA designs using the majority of KU040 or KU060 FPGA resources while running at clock rates over 150 MHz, the module may require more power than is available. If the module attempts to draw more than allowed per its specification, the module protects itself and reverts to a default FPGA personality. Refer to the getting started guide for your module or contact NI support for more information

Onboard DRAM

Memory size	4 GB (2 banks of 2 GB)
DRAM clock rate	1064 MHz
Physical bus width	32 bit
LabVIEW FPGA DRAM clock rate	267 MHz
LabVIEW FPGA DRAM bus width	256 bit per bank
Maximum theoretical data rate	17 GB/s (8.5 GB/s per bank)

Analog Input



Notice The maximum input signal levels are valid only when the module is powered on. To avoid permanent damage to the PCIe-5763, do not apply a signal to the device when the module is powered down.

General Characteristics

Number of channels	4, single-ended, simultaneously sampled
Connector type	SMA
Input impedance	50 Ω
Input coupling	AC or DC ⁵
Sample Rate	
Internal Sample Clock	500 MHz
External Sample Clock	500 MHz ⁶
Analog-to-digital converter (ADC)	ADS54J69, 16-bit resolution

Typical Specifications

2.03 V _{pp} (10.15 dBm) at 10 MHz 1.97 V _{pp} (9.87 dBm)
1.97 V _{pp} (9.87 dBm)
$\pm 0.1 \text{ dB}$ at 10 MHz
±1% at DC
±41 μV
±225 μV
0.07 MHz to 225 MHz
DC to 225 MHz ⁹

⁵ Only one analog input path type is populated.

⁶ You must provide a 1 GHz clock at the CLK/REF IN front panel connector to enable this rate.

Normalized to 10 MHz.

⁸ Upper -3 dB bandwidth limited by ADC decimation filter.

Table 4. Single-Tone Spectral Performance

	AC-C	Coupled	DC-Coupled		
	Input Frequency		Input Frequency		
	10.1 MHz	123.1 MHz	10.1 MHz	123.1 MHz	
SNR ⁹ (dBFS)	73.7	71.8	71.7	70.6	
SINAD ⁹ (dBFS)	73.5	71.7	70.7	70.5	
SFDR (dBc)	-85.6	-87.7	-77.2	-86.1	
ENOB ¹⁰ (bits)	11.9	11.6	11.5	11.4	

Table 5. Noise Spectral Density

Module	nV/rt (Hz)	dBm/Hz	dBFS/Hz
AC-coupled	9.5	-147.4	-157.5
DC-coupled	11.8	-145.6	-155.4



Note Noise spectral density is verified using a 50 Ω terminator connected to the input.

 $^{^9\,}$ Measured with a -1 dBFS signal and corrected to full-scale. 1 kHz resolution bandwidth. $^{10}\,$ Calculated from SINAD and corrected to full scale.

Figure 1. AC-Coupled Single Tone Spectrum (10.1 MHz, -1 dBFS, 1 kHz RBW), Measured

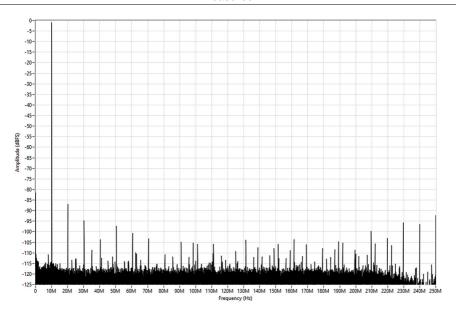


Figure 2. AC-Coupled Single Tone Spectrum (123.1 MHz, -1 dBFS, 1 kHz RBW), Measured

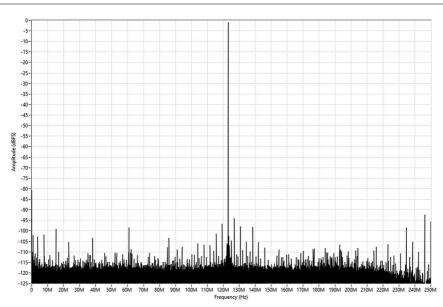


Figure 3. DC-Coupled Single Tone Spectrum (10.1 MHz, -1 dBFS, 1 kHz RBW), Measured

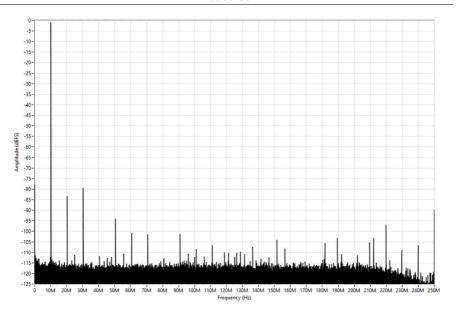
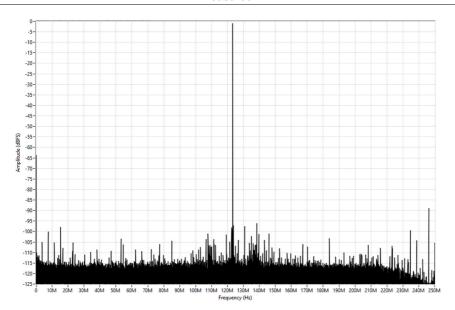


Figure 4. DC-Coupled Single Tone Spectrum (123.1 MHz, -1 dBFS, 1 kHz RBW), Measured



Channel-to-channel crosstalk AC-coupled, characteristic		
10 MHz	-87 dB	
100 MHz	-89 dB	
225 MHz	-85 dB	
Channel-to-channel crosstalk DC-coupled, characteristic		
1 MHz	-94 dB	
100 MHz	-83 dB	
225 MHz	-78 dB	

Figure 5. AC-Coupled Frequency Response, Measured

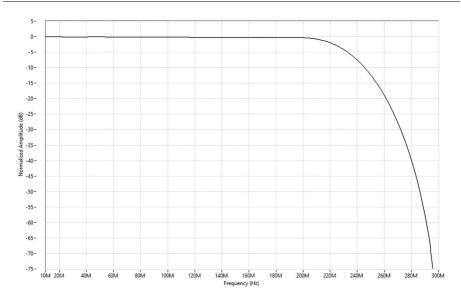
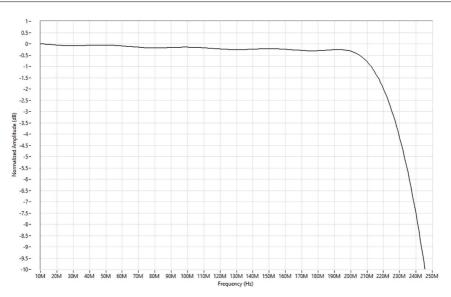


Figure 6. AC-Coupled Frequency Response Zoomed In, Measured



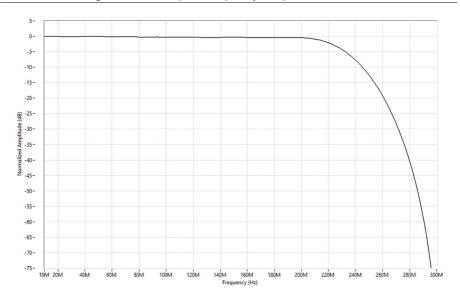
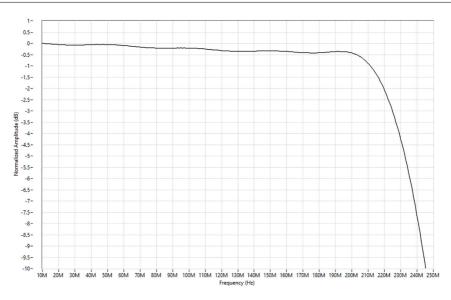
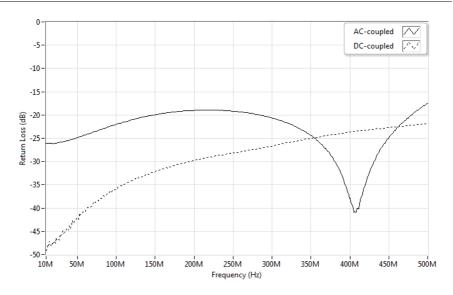


Figure 8. DC-Coupled Frequency Response Zoomed In, Measured





REF/CLK IN

General Characteristics

Connector type	SMA
Input impedance	50 Ω
Input coupling	AC
Reference input voltage range	$0.3~\mathrm{V_{pp}}$ to $4~\mathrm{V_{pp}}$
Sample Clock input voltage range	$0.3~\mathrm{V_{pp}}$ to $4~\mathrm{V_{pp}}$
Absolute maximum voltage	$\pm 12 \text{ V DC}, 4 \text{ V}_{pp} \text{ AC}$
Duty cycle	45% to 55%
Onboard reference timebase stability	±0.5 ppm
Sample Clock jitter ¹¹	
AC-coupled	135 fs RMS
DC-coupled	142 fs RMS

¹¹ Integrated from 1 kHz to 10 MHz. Includes the effects of the converter aperture uncertainty and the clock circuitry jitter. Excludes trigger jitter.

Table 6. Clock Configuration Options

Clock Configuration	External Clock Type	External Clock Frequency	Description
Internal Reference Clock ¹²	_	_	The internal Sample Clock locks to an onboard voltage-controlled temperature compensated crystal oscillator (VCTCXO).
Internal Baseboard Reference Clock	_	10 MHz	The internal Sample Clock locks to the 10 MHz Reference Clock provided from the FPGA baseboard.
External Reference Clock (REF/CLK IN)	Reference Clock	10 MHz ¹³	The internal Sample Clock locks to an external Reference Clock, which is provided through the REF/CLK IN front panel connector.
External Sample Clock (REF/CLK IN)	Sample Clock	1 GHz ¹⁴	An external Sample Clock can be provided through the REF/CLK IN front panel connector.

Default clock configuration.
The PLL Reference Clock must be accurate to ±25 ppm.
The ADC sample rate is 500 MS/s with a 1 GHz clock.

Figure 10. AC-Coupled Phase Noise with 182.6 MHz Input Tone, Measured

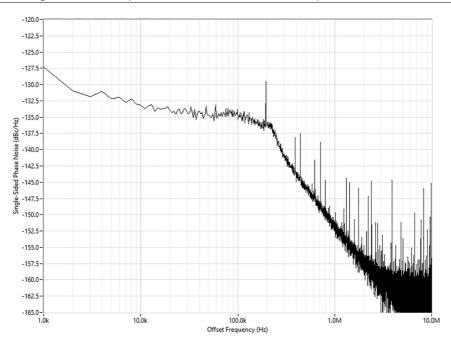
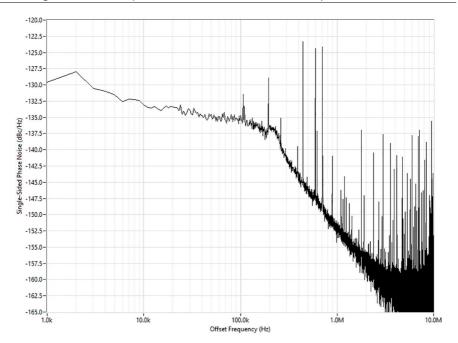


Figure 11. DC-Coupled Phase Noise with 182.6 MHz Input Tone, Measured



Bus Interface

Card edge form factor	PCI Express Gen-3 x8
Slot compatibility	x8 and x16 PCI Express

Maximum Power Requirements



Note Power requirements are dependent on the contents of the LabVIEW FPGA VI used in your application.

+3.3 V	4.5 A
+12 V	5 A
Maximum total power	75 W

Physical

Dimensions (including I/O bracket, not including connectors)	12.6 cm × 26.3 cm × 4 cm (5.0 in. × 10.4 in. × 1.6 in.)
Weight	990 g (35 oz)
PCI Express mechanical form factor	Standard height, three-quarter length, double slot
Integrated air mover (fan)	Yes
Maximum rear panel exhaust airflow	84 m ³ /h (50 CFM) (without any chassis impedance)

Environmental

Maximum altitude	2,000 m (800 mbar) (at 25 °C ambient temperature)
Pollution degree	2

Indoor use only.

Operating Environment

Operating temperature, local ¹⁵	0 °C to 45 °C
Operating humidity	10% to 90% RH, noncondensing

Storage Environment

Ambient temperature range	-20 °C to 70 °C
Relative humidity range	5% to 95% RH, noncondensing

For PCI Express adapter cards with integrated air movers, NI defines the local operational ambient environment to be at the fan inlet. For cards without integrated air movers, NI defines the local operational ambient environment to be 25 mm (1 in.) upstream of the leading edge of the card.

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